

Title (en)

SEAL STRUCTURE FOR ELECTRONIC EQUIPMENT

Title (de)

DICHTUNGSSTRUKTUR FÜR EINE ELEKTRONISCHE VORRICHTUNG

Title (fr)

STRUCTURE DE JOINT D' ETANCHEITE POUR EQUIPEMENT ELECTRONIQUE

Publication

EP 2320719 A4 20130925 (EN)

Application

EP 09809751 A 20090806

Priority

- JP 2009063912 W 20090806
- JP 2008217678 A 20080827
- JP 2009071689 A 20090324

Abstract (en)

[origin: EP2320719A1] Disclosed is a seal structure that seals a portion between a case and a lid that are mutually combined to form a casing for an electronic equipment. In order to enhance the shape retention of a gasket consisting of a rubber, a resin film is formed integrally with the gasket. The seal structure is advantageous in that the integration of the resin film does not lead to an enhancement in the reactive force of the gasket, damage to the casing for the electronic equipment by a high reactive force of the gasket does not occur, and, further, the casing can easily be assembled. The seal structure comprises a gasket, which is mounted in a nonbonding manner on a portion between the case and the lid and is interposed between the case and the lid in a compressed state when a case lid assembly is formed, and a resin film formed integrally with the gasket from the viewpoint of enhancing the shape retention of the gasket. The gasket has a site that is compressed between the case and the lid when the case lid assembly is formed, and a site that is not compressed between the case and the lid when the case lid assembly is formed. The resin film is integrated with the site which is not compressed.

IPC 8 full level

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CPC (source: EP US)

F16J 15/104 (2013.01 - EP US); **H05K 5/061** (2013.01 - EP US)

Citation (search report)

- [XAI] US 5564714 A 19961015 - KATSUNO NOBUHIRO [JP], et al
- See references of WO 2010024097A1

Cited by

EP3396215A4; US10960585B2

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DOCDB simple family (publication)

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